# PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Hyun-Sik PARK	06/26/2007
Ky-Hyun HAN	06/26/2007

## **RECEIVING PARTY DATA**

Name:	Hynix Semiconductor Inc.	
Street Address:	San 136-1, Ami-ri, Bubal-eub	
City:	lchon-shi, Kyoungki-do	
State/Country:	ountry: KOREA, REPUBLIC OF	
Postal Code:	ostal Code: 467-860	

### PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11768366	

### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 123037-0003

NAME OF SUBMITTER: Yoon S. Ham

Total Attachments: 1

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OP \$40,00

PATENT REEL: 019479 FRAME: 0456

	Docket No.:					
		ASSIGNMENT				
	n consideration of the premises ar iciency of which is hereby acknow 1) PARK, Hyun-Sik		consideration in hand paid, the receipt and			
	3)	4)				
	5)	6)				
Sen 860, title	niconductor Inc. having a place of Republic of Korea, its successors and interest for the United States	of business at <u>San 136-1, Am</u> s and assigns (hereinafter d of America as defined in 3: WITH BULB TYPE RE	sells, assigns and transfers unto <b>Hvnix</b> ni-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-lesignated "ASSIGNEE") the entire right, 5 U.S.C. 100 in the invention entitled ICESS GATE AND METHOD FOR			
(a)	for which an application for United United States Patent Application No	I States Letters Patent was filed	on and identified by			
(b)						
exte unde inter attor A and e its su for p	nsions, divisions, reissues, continer the International Convention for the International Convention for the International Convention for the International application with the undersigned hereby agrees to trabbtaining original, divisional, reissued or accessors, assigns and legal representativatent based thereon, growing out of or research.	untions, or continuations-in- r the Protection of Industria s, assigns and legal represe shall hereafter act on behalf of unsfer a like interest, and to render extended Letters Patent of the United es, and without further remunerated elated to the said invention; and it	h may be granted therefore and any and all -part thereof, and the right to all benefits all Property to the said ASSIGNEE, for its entatives; the undersigned agrees that the of said ASSIGNEE;  r all necessary assistance in making application for nited States, upon request of the said ASSIGNEE, tion, in and to any improvements, and applications to execute any papers by the said ASSIGNEE, its Still protection and title in and to the invention			
SIGN	IED on the date indicated aside my signa	ture:				
1)	ame: PARK, Hyun-Sik		une 26, 2007			
N	ame: PARK, Hyun-Sik	Dat	(6)			
2}	how by 140	Wi.	une 26, 2007			
N	ame: HAN, Ky-Hyun	Dat				
3)						
	ame:	Dat	e:			
	ame;	Dat	le;			
5)						
N	ame;	Dat	:E:			

RECORDED: 06/26/2007

PATENT REEL: 019479 FRAME: 0457